

SOT1016-1

plastic thin fine-pitch ball grid array package; 160 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA160
Package type industry code	TFBGA160
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-7-2007

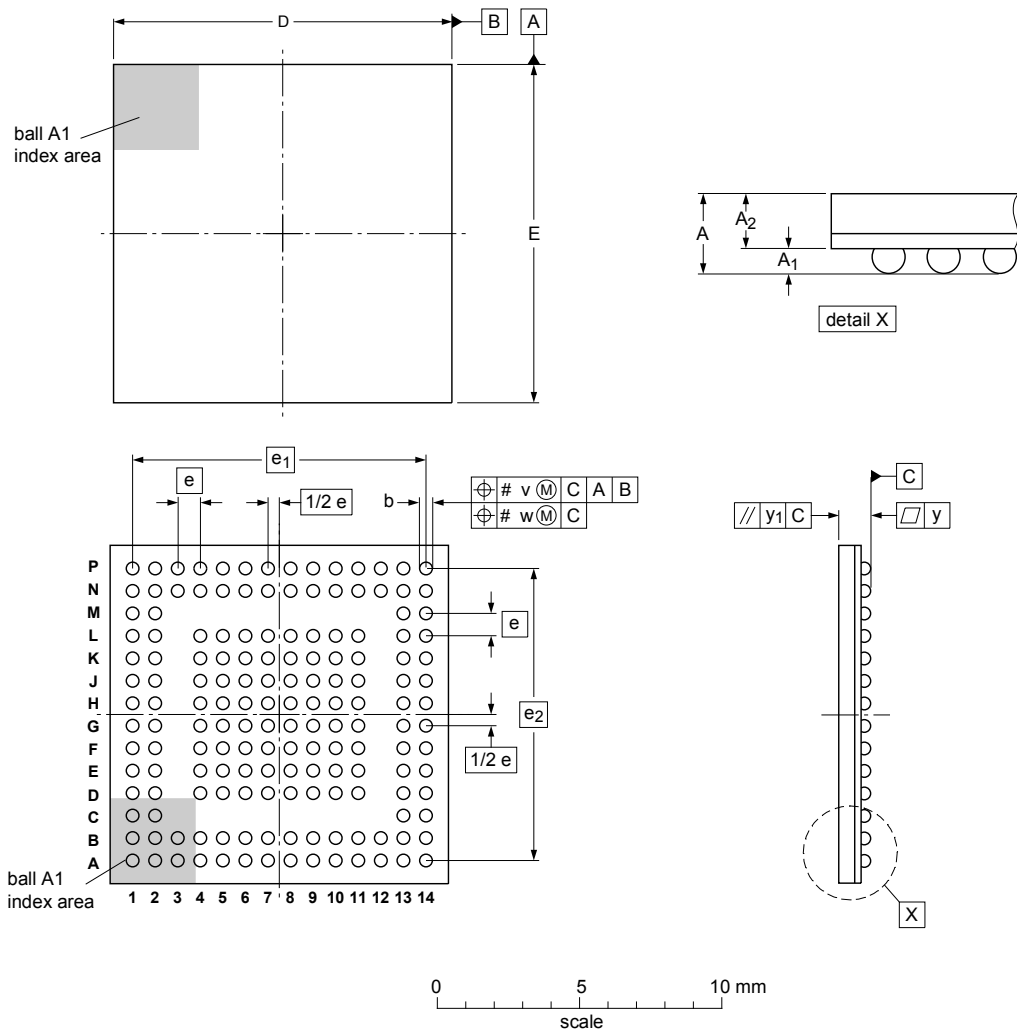
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.65	-	0.8	0.8	mm
n ₂	actual quantity of termination	-	-	160	-	



2. Package outline

TFBGA160: plastic thin fine-pitch ball grid array package; 160 balls SOT1016-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.2	0.4 0.3	0.80 0.65	0.5 0.4	12.1 11.9	12.1 11.9	0.8	10.4	10.4	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1016-1		---				07-06-20 07-07-27

Fig. 1. Package outline TFBGA160 (SOT1016-1)

3. Legal information

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